METHOD OF FORMING BALL GRID ARRAY CONTACTS

ABSTRACT OF THE DISCLOSURE

The invention is to a method for forming solder contact balls (12) for a ball grid array semiconductor device. A solder sheet (15) is formed having solder elements (18) extending out at least one side of the solder sheet (15). The solder sheet is placed over and aligned on a semiconductor package (50) on which solder balls (12) are to be electrically connected to contact areas (51). The solder sheet (15) is aligned with one solder element (18) over each contact area (51). The package (50) and solder sheet (15) is heated to cause the solder elements (18) on the solder sheet (15) to separate and reflow such that the surface tension of the reflowed solder of each solder element (18) forms a solder ball (12) over a contact area (51).

Figure 2

This Sheet Has Been Replaced

